

Description of Change:

Convert to Sumitomo G-600 Mold Compound in 28L SOIC package at ALPH, Thailand assembly site.

Impacts to Data Sheet:

NONE

Reason for Change:

Improved Moisture Characteristics to allow the higher Reflow temperatures required by Lead Free applications.

Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date Code, Device Marking, Ship Container Marking)

DATE CODE and Traceability code.

Devices

MCP23016

PIC14000

PIC16C55

PIC16C557

PIC16C55A

PIC16C55A

PIC16C57

PIC16C57

PIC16C57C

PIC16C57C

PIC16C62A

PIC16C62B

PIC16C63

PIC16C63A

PIC16C642

PIC16C66

PIC16C72

PIC16C72A

PIC16C73A

PIC16C73B

PIC16C745

PIC16C76

PIC16C773

PIC16CR57B

PIC16CR57C

PIC16CR63
PIC16CR72
PIC16F72
PIC16F73
PIC16F737
PIC16F76
PIC16F767
PIC16F870
PIC16F872
PIC16F873
PIC16F873A
PIC16F876
PIC16F876A
PIC16FR55
PIC16FR57
PIC16FR62A
PIC16FR63
PIC16FR66
PIC16FR72
PIC16FR73A
PIC16FR76
PIC16LC557
PIC16LC55A
PIC16LC55A
PIC16LC57C
PIC16LC57C
PIC16LC62A
PIC16LC62B
PIC16LC63
PIC16LC63A
PIC16LC642
PIC16LC66
PIC16LC72
PIC16LC72A
PIC16LC73A
PIC16LC73B
PIC16LC76
PIC16LC773
PIC16LCR57C
PIC16LCR63
PIC16LF72
PIC16LF73

PIC16LF737
PIC16LF76
PIC16LF767
PIC16LF870
PIC16LF872
PIC16LF873
PIC16LF873A
PIC16LF876
PIC16LF876A
PIC16LFR62A
PIC16LFR63
PIC16LFR66
PIC16LFR72
PIC16LFR73A
PIC16LFR76
PIC18C242
PIC18C252
PIC18F2220
PIC18F2320
PIC18F2331
PIC18F242
PIC18F2431
PIC18F2439
PIC18F248
PIC18F252
PIC18F2539
PIC18F258
PIC18LC242
PIC18LC252
PIC18LF2220
PIC18LF2320
PIC18LF2331
PIC18LF242
PIC18LF2431
PIC18LF2439
PIC18LF248
PIC18LF252
PIC18LF2539
PIC18LF258
PICFR57
TC514

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